



Click [here](#) for the 3D model.

Dimensions

| | |
|---|-----------------|
| L | 1.6mm +/-0.2mm |
| W | 3.2mm +/-0.2mm |
| T | 0.8mm +/-0.10mm |
| P | 0.8mm +/-0.10mm |

Packaging Specifications

| | |
|--------------------|------------------------|
| Packaging | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000 |

General Information

| | |
|--------------------------|--|
| Series | Array Auto COG Flex |
| Style | SMD Array |
| Description | SMD, MLCC, Array, Flex Termination, Automotive Grade |
| Features | Automotive Grade |
| RoHS | Yes |
| Termination | Flexible Termination |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |
| Typical Component Weight | 18 mg |
| Notes | Last Time Buy Date (LTB): May 30th, 2024. |
| Chip Size | 0612 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---------------------------|
| Capacitance | 27 pF |
| Measurement Condition | 1MHz 1.0Vrms |
| Capacitance Tolerance | 5% |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |